Sessions Monday, April 7

08:30 - 09:00	**Registration**	
09:00 - 12:30	**Tutorial + Workshop**	
12:30 - 14:00	**Lunch Break**	
14:00 - 15:40	**Opening Session** **Session Chair:**	
14:00 - 14:10	R1	**Opening Remarks:**
14:10 - 14:20	W1	**Welcome Address: Sergio Galbiati (LFoundry)**
14:20 - 14:50	K1	**Keynote 1: Roberto Zafalon (ST Microelectronics)** “The Renaissance of Nanoelectronics and Smart Systems industry: More than Moore in the Italian eco-system”
14:50 - 15:40	I1	**Invited Talk: Thomas Sonderman (BISTel)** Title tba
15:40 - 16:10	**Break**	
16:10 - 17:10	**Session 1:** **Session Chair:**	
16:10 - 16:40	1.1	**Andre Holfeld (GLOBALFOUNDRIES)** Process Control Monitoring Improvements using a fab level metrology APC application
16:40 - 17:10	1.2	**Clemens Schwenke (Dresden University of Technology)** Sense and React in Future Factory Automation
17:10 - 17:50	**Poster Presentation**	
17:50 - 19:00	**Reception, Posters, Exhibition**	

Sessions Tuesday, April 8

08:30 - 09:00	**Registration**			
09:00 - 11:10	**Opening Session** **Session Chair:**			
09:00 - 09:10	R2	**Opening Remarks:**		
09:10 - 09:40	K2	**Keynote 2:** **Martin Schellenberger (Fraunhofer IISB)** Title tba		
09:40 - 10:15	I2	**Invited Talk 2:** **Michael Liehr (CNSE)** At a crossroads in scaling		
10:15 - 11:15	**Session 2:** **Session Chair:**			
10:15 - 10:45	2.1	**James Moyne (Applied Materials)** The International Technology Roadmap for Semiconductor Manufacturing's (ITRS) Big Data Roadmap		
10:45 - 11:15	2.2	**Klaus Sandtner (Infineon Technologies Austria AG)** Visualization of the Lot Flow in a Semiconductor Power Fab with High Complexity		
11:15 - 11:45	**Break**			
11:45 - 13:15	**Session 2:** **Session Chair:**		**Session 3:** **Session Chair:**	
11:45 - 12:15	2.3	**Peter Henoeckl (Infineon Technologies Austria AG)** Factory Integrated Robotic Effector - An Autonomous Robotic System for Handling Wafer Cassettes	3.1	**Georg Roeder (Fraunhofer IISB)** Application of Virtual Metrology Techniques to combine Process Information from DOEs and individual Experiments performed during Equipment Assessment
12:15 - 12:45	2.4	**Cristina De Luca (Infineon Technologies Austria AG)** A Look into the Future of Enabling 300mm Power Technologies and Automation Challenges	3.2	**Paolo Ciotti (Marsica Innovation & Technology S.r.l.)** An Adaptive Exponential Weighted Moving Average Filter for Overlay Correction in Photolithography
12:45 - 13:15	2.5	**Jan Driessen (NXP Semiconductors)** WAIT-TIME-WASTE opportunities in SECS/GEM-based 200mm fabs (INTEGRATE)	3.3	**Alexander Tobisch (Fraunhofer IISB)** Optical metrology for full-field wafer nanotopography inspection
13:15 - 14:40	**Lunch Break**			
14:40 - 16:10	**Session 2:** **Session Chair:**		**Session 4:** **Session Chair:**	
14:40 - 15:10	2.6	**Thomas Wagner (Dresden University of Technology)** Automatic Generation of Simulation Models of Automated Material Handling Systems in Semiconductor Manufacturing	4.1	**Peter Scheibelhofer (ams AG)** Applied Multivariate Monitoring of Wafer Acceptance Tests
15:10 - 15:40	2.7	**Bert Müller (AIS Automation Dresden GmbH)** Flexible Total Cost of Ownership Calculation (TCO) tool to calculate and plan manufacturing lines with Open Source Software Technologies	4.2	**Marco Bagagiolo (STMicroelectronics)** First wafer effect on epitaxial reactors with parallel coordinate visualization
15:40 - 16:10	2.8	**Alan Weber (Cimetrix)** Analyzing Event Data: Where Does All the Time Go?SECS/GEM-based 200mm fabs (INTEGRATE)	4.3	**Gerd Fischer (SolarWorld Innovations GmbH)** Yield Enhancement in Advanced Silicon Photovoltaic Production based on TCAD Device Simulation and Statistical Analysis

16:10 - 17:10	**Break & Postersession**			
17:10 - 18:40	**Session 2:** **Session Chair:**		**Session 4:** **Session Chair:**	
17:10 - 17:40	2.9	**Sophia Keil (Dresden University of Technology)** Exploring the effects of lot size on cycle time and throughput in semiconductor industry – an empirical study	4.4	**Sang-Ho Lee (Samsung Electronic)** Semiconductor Equipment Sensor Data Analysis for Yield Enhancement: How to Deal with Big-Data?
17:40 - 18:10	2.10	**Israel Tirkel (Ben-Gurion University of the Negev)** The Impact of Variability on Cycle Time Reduction	4.5	**Justin Wong (BISTel America)** How to implement an FDC system successfully – A methodical approach with a framework of tools in data collection, data summarization, data mining, univariate FDC and multivariate FDC modeling.
18:10 - 18:40	2.11	**Mike Gißrau (X-FAB Dresden)** The influence of human operations on the factory performance of a high-mix low-volume ASIC facility – A case study	4.6	**Roland Willmann (PEERGroup GmbH)** Fast Machine Ramp-up Through a Comprehensive Equipment Automation Platform
18:40 - 19:10	**Break**			
19:10 - 22:00	**Sightseeing and Conference Dinner**			

Sessions Wednesday, April 9

08:30 - 09:00	**Registration**			
09:00 - 11:10	**Opening Session** **Session Chair:**			
09:00 - 09:10	R2	**Opening Remarks:**		
09:10 - 09:40	K3	**Keynote 3:** **Andreas Wilde** (**Executive Director ENIAC Joint Undertaking)** Title tbd		
09:40 - 10:20	I3	**Invited Talk 3:** **Sophia Keil (Dresden University of Technology)** Title tbd		
10:20 - 10:30		**Dr. Zwack (Texas Instruments)** Information apc|m 2015		
10:30 - 11:00	I4	**Invited Talk 4:** **Tomoya Tanaka (Panasonic Corporation)** Improvement of Overall Equipment Efficiency by Virtual Metrology using Equipment data in Reactive Sputtering of Titanium Nitride		
11:00 - 11:30	**Break**			
11:30 - 13:30	**Session 1:** **Session Chair:**		**Session 5:** **Session Chair:**	
11:30 - 12:00	1.3	**Kenneth Harris (PDF Solutions)** An Analysis Platform for Variability Reduction in “Big Data” Manufacturing Environments	5.1	**Chanhee Park (Korea University, Samsung Electronics)** Virtual Metrology Modeling of Time-Dependent Spectroscopic Signals Using a Fused Lasso Algorithm
12:00 - 12:30	1.4	**Q. Peter He (Tuskegee University)** A New Virtual Metrology Approach for Semiconductor Manufacturing Processes	5.2	**Rupert Wagner (Texas Instruments Deutschland GmbH)** Development of a Plasma Etch Insitu Chamber Clean (ICC) and Analysis of etch plasma problems using a SEER plasma sensor
12:30 - 13:00	1.5	**Jueun Kwak (Yonsei University)** Incremental Clustering-Based Semiconductor Fault Monitoring in Non-stationary Stream Data Situation	5.3	**Haegyu Jang (Sungkyunkwan University)** Plasma Etching Endpoint Detection of Dielectric Layers with RF Impedance Monitoring and modified K-means Cluster Analysis
13:00 - 13:30	1.6	**Jin Wang (Auburn University)** Non-threaded Run-to-Run Control	5.4	**Martin Bäßler (AMTC)** Process Stability in Photo Mask Manufacturing
13:30 - 13:40	**Closing Remarks**			
13:40 - 15:00	**Lunch**			